



Intel® Q57 Express Chipset
(Intel® BD82Q57 PCH)

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Specifications

Essentials

Status	Launched
Launch Date	Q1'10
Embedded Options Available	Yes
Lithography	65 nm
TDP	5.1 W
Recommended Customer	
Conflict Free	Yes
Datasheet	Link
Product Brief	Link

Graphics Specifications

Integrated Graphics ‡	Yes
Graphics Output	HDMI, Display Port, DVI, VGA
Intel® Clear Video Technology	Yes
# of Displays Supported ‡	2
Macrovision* License Required	No

Expansion Options

PCI Support	4 Devices
PCI Express Revision	2.0 (2.5 GT/s)
PCI Express Configurations ‡	x1, x2, x4
Max # of PCI Express Lanes	8

I/O Specifications

USB Revision	2.0
# of USB Ports	14
Total # of SATA Ports	6
Integrated LAN	10/100/1000 Mbps Ethernet Support

Package Specifications

Max CPU Configuration	1
T _{CASE}	111°C
Package Size	27mm x 27 mm
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) ‡	Yes
Intel® vPro Technology ‡	Yes
Intel® ME Firmware Version	6.0; 6.1
Intel® Remote PC Assist Technology	Yes
Intel® Quick Resume Technology	Yes
Intel® Quiet System Technology	Yes
Intel® HD Audio Technology	Yes
Intel® AC97 Technology	Yes
Intel® Matrix Storage Technology	Yes

Intel® Platform Protection Technology

Trusted Execution Technology ‡	Yes
Anti-Theft Technology	Yes

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PCN/MDDS Information

SLGZW

904131: [PCN](#) | [MDDS](#)

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not

confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

The Recommended Customer 1,000-unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

WARNING: Altering clock frequency and/or voltage may: (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the processor beyond its specifications. Intel assumes no responsibility that the processor, including if used with altered clock frequencies and/or voltages, will be fit for any particular purpose. For more information, visit <http://www.intel.com/content/www/us/en/gaming/overclocking/overclocking-intel-processors.html>

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